



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
custreq@latticesemi.com

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Package: 400 caBGA
Total Device Weight 0.719 Grams

Package Code:

BG400

Products:

LCMXO3-9400

Assembly: ASEK

Size (mm): 17 x 17

Lead pitch (mm): 0.8

MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.67%	0.0120	1.67%	0.0120	Silicon chip	7440-21-3	100.00%	Die size: 5.092 x 4.968 mm
Mold Compound	55.60%	0.3999	48.65%	0.3499	Silica	60676-86-0	87.50%	Mold Compound: Kyocera KE-G1250AHT
			3.61%	0.0260	Epoxy resin	-	6.50%	
			3.06%	0.0220	Phenol Resin	-	5.50%	
			0.28%	0.0020	Carbon Black	1333-86-4	0.50%	
D/A Epoxy	0.60%	0.0043	0.48%	0.00345	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel 2100A
			0.12%	0.00086	Esters & resins	-	20.00%	
Wire	0.39%	0.0028	0.379%	0.00273	Copper (Cu)	7440-50-8	97.20%	AuPCC+, 0.02mm dia
			0.010%	0.00007	Palladium (Pd)	7440-05-3	2.50%	
			0.001%	0.00001	Gold (Au)	7440-57-5	0.30%	
Solder Balls	15.55%	0.1118	15.00%	0.1079	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.47%	0.0034	Silver (Ag)	7440-22-4	3.00%	
			0.08%	0.0006	Copper (Cu)	7440-50-8	0.50%	
Substrate	10.22%	0.0735	3.27%	0.0235	BT Resins	-	32.00%	BT Resin CCL-HL832NX-A
			6.95%	0.0500	Glass fiber	65997-17-3	68.00%	
Foil	5.24%	0.0377	4.06%	0.0292	Copper	7440-50-8	77.39%	
			1.00%	0.0072	Nickel plating	7440-02-0	19.02%	
			0.19%	0.0014	Gold plating	7440-57-5	3.59%	
Solder Mask	10.74%	0.0773	2.53%	0.0182	Solvent naphtha (petroleum)	64742-94-5	23.52%	Solder mask PSR4000 AUS 320
			0.63%	0.0045	Naphthalene	91-20-3	5.87%	
			1.58%	0.0114	Phosphin oxide derivative	-	14.70%	
			1.58%	0.0114	Talc	14807-96-6	14.70%	
			1.89%	0.0136	Dipropylene glycol monomethyl Ether	34590-94-8	17.63%	
			1.58%	0.0114	Epoxy Resin	85954-11-6	14.70%	
			0.95%	0.0069	Barium Sulfate	7727-43-7	8.88%	

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